

# **Specification for TFT**

# AFY240320A0-2.4INTH-R



**Revision** O

А	Orient Display
FY	ТFT Туре
240320	Resolution 240 x 320
A0	Serial A0
2.4	2.4", Module Dimension 42.72 x 58.50 x 3.30 mm
1	IPS Display
Ν	Top: -20~+70°C; Tstr: -30~+80°C
Т	Transmissive
Н	High Brightness, 800 cd/m2
R	Resistive Touch Panel
/	Controller ST7789V Or Compatible
1	MCU/18bit RGB Interface













### **REVISION RECORD**

Rev No.	Rev date	Contents	Remarks
0	2019-11-28	First release	Preliminary

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## **1. GENERAL INFORMATION**

No.	Item	Contents	Unit
1	LCD size	2.4 inch (Diagonal)	/
2	Display mode	Normally black/Transmissive/Anti-glare	/
3	Viewing direction(eye)	FREE	/
4	Gray scale inversion direction	-	/
5	Resolution(H*V)	240 *320 Pixels	/
6	Module size (L*W*H)	42.72*58.50*3.30	mm
7	Active area (L*W)	36.72*48.96	mm
8	Pixel pitch (L*W)	0.153*0.153	mm
9	Interface type	RGB interface	/
10	Color Depth	16.7M	/
11	Module power consumption	TBD	W
12	Back light type	LED	/
13	Driver IC	ST7789V or compatible	/
14	Weight	TBD	g

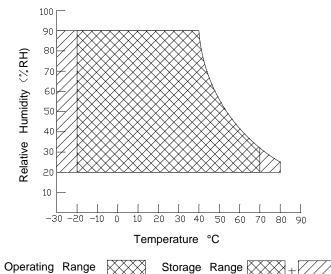
# 2. ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Min.	Max.	Unit	Note
Power supply input voltage for TFT	VDD	-0.3	4.6	V	
Backlight current (normal temp.)	ILED	-	100	mA	
Operation temperature	Тор	-20	+70	°C	Note1
Storage temperature	Tst	-30	+80	°C	Note1
Humidity	RH	-	90%(Max60 °C)	RH	Note1

Note1:

1). The relative humidity and temperature range are as below sketch, 90% RH Max.

2). The maximum wet bulb temperature  $\leq 40^{\circ}$ C and without dewing.



# **3. ELECTRICAL CHARACTERISTICS**

DC CHARACTERISTICS(at Ta=25°C)

Item	Symbol	Min.	Тур.	Max.	Unit	Note
Power supply input voltage	VCC	2.65	2.8	3.3	V	
I/O logic voltage	VDDIO	-	1.8	-	V	=VCC
Input voltage 'H' level	VIH	0.7VDDIO	-	VDDIO	V	
Input voltage 'L' level	VIL	VSS	-	0.3VDDIO	V	
Power supply current	IVDD	-	9	-	mA	

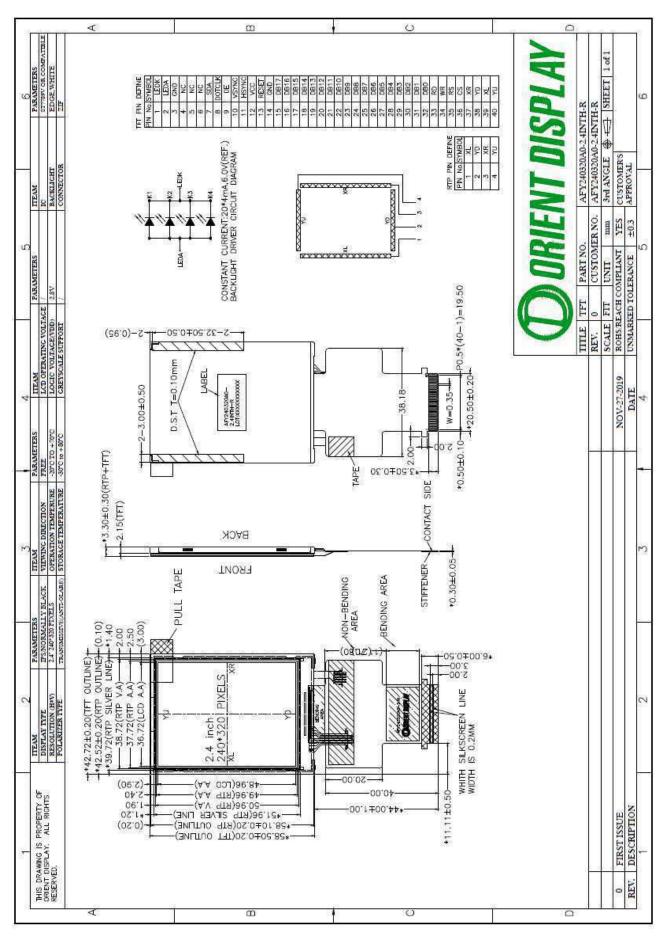
# 4. BACKLIGHT CHARACTERISTICS

Item	Symbol	Min.	Тур.	Max.	Unit	Note
LED forward voltage	VF		6.0		V	IF=20*4mA
LED forward current	IF	-	80	-	mA	
LED power consumption	PLED	-	0.256	-	W	Note1
Number of LED	-		4		PCS	
Connection mode	-		4 in parallel		/	
LED life-time	-	20000	-	-	Hrs	Note2

Note1 : Calculator value for reference : IF\*VF = PLED

Note2 : The LED life-time define as the estimated time to 50% degradation of initial brightness at Ta=25°C and IF =80mA. The LED lifetime could be decreased if operating IF is larger than 80mA.

# 5. EXTERNAL DIMENSIONS



Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Remark	Note
Response time	Tr+ Tf		-	35	45	ms	FIG.1	Note 1
Contrast ratio	Cr	-	500	750	-	-	FIG.2	Note 2
Surface Iuminance	Lv	θ=0°	600	800	-	cd/m <sup>2</sup>	FIG.2	Note 3
Luminance uniformity	Yu	θ=0°	75	80	-	%	FIG.2	Note 4
NTSC	-	θ=0°	-	50	-	%	FIG.2	Note 5
Viewies ende		Ø <b>=</b> 90°	70	80	-	deg	FIG.3	Note 6
	θ	Ø=270°	70	80	-	deg	FIG.3	
Viewing angle		Ø <b>=</b> 0°	70	80	-	deg	FIG.3	
		Ø=180°	70	80	-	deg	FIG.3	
	Red x			TBD		-		
	Red y			TBD		-		
	Green x			TBD		-		
CIE (x,y)	Green y	θ=0° ∅=0°	Тур	TBD	Тур	-	FIG.2	Note F
chromaticity	Blue x	©=0° Ta=25°C	-0.04	TBD	+0.04	-	CIE1931	Note 5
	Blue y	10-20 0		TBD		-		
	White x			TBD		-		
	White y			TBD		-		

# 6. ELECTRO-OPTICAL CHARACTERISTICS

### Note1. Definition of response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black"state.Rise time  $(T_{ON})$  is the time between photo detector output intensity changed from 90% to 10%. And fall time  $(T_{OFF})$  is the time between photo detector output intensity changed from 10% to 90%. For additional information see FIG1.

### Note2.Definition of contrast ratio

Contrast ratio(Cr) is defined mathematically by the following formula.

For more information see FIG.2.

Contrast ratio= Luminance measured when LCD on the "White" state

Luminance measured when LCD on the "Black" state

Measured at the center area of the LCD

#### Note3.Definition of surface luminance

Surface luminance is the luminance with all pixels displaying white.

For more information see FIG.2.

Lv = Average Surface Luminance with all white pixels(P1,P2,P3, .....,Pn)

#### Note4.Definition of luminance uniformity

The luminance uniformity in surface luminance is determined by measuring luminance at each test position 1 through n, and then dividing the maximum luminance of n points luminance by minimum luminance of n points luminance. For more information see FIG.2.

 $Yu = \frac{\text{Minimum surface luminance with all white pixels (P1,P2,P3,....,Pn)}{Maximum surface luminance with all white pixels (P1,P2,P3,....,Pn)}$ 

 $Tu = \frac{1}{Maximum surface luminance with all white pixels (P1,P2,P3,....,Pn)}$ 

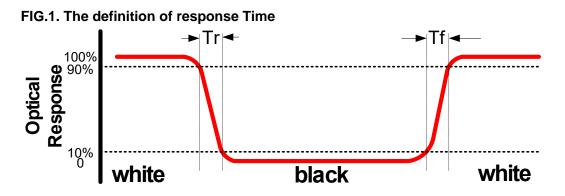
#### Note5. Definition of color chromaticity (CIE1931)

CIE (x,y) chromaticity,The x,y value is determined by screen active area center position P5.For more information see FIG.2.

#### Note6. Definition of viewing angle

Viewing angle is the angle at which the contrast ratio is greater than 10. angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG.3.

For viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope or DMS series Instruments or compatible. For contrast ratio, Surface Luminance, Luminance uniformity and CIE, the testing data is based on TOPCON's BM-5or BM-7 photo detector or compatible.



# FIG.2. Measuring method for contrast ratio, surface luminance,

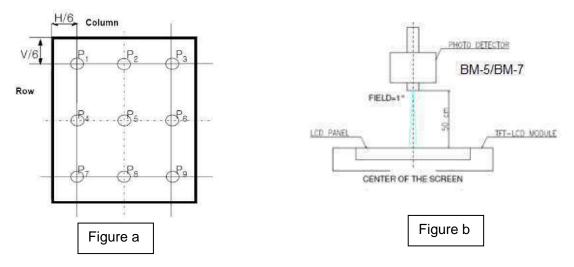
luminance uniformity, CIE (x,y) chromaticity

H,V : Active area

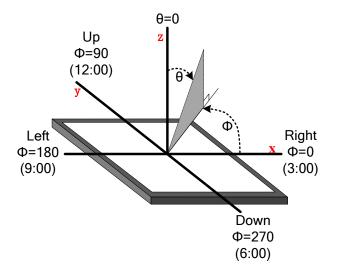
Light spot size  $\emptyset$ =5mm(BM-5) or  $\emptyset$ =7.7mm (BM-7)50cm distance or compatible distance from the LCM surface to detector lens.

Test spot position : see Figure a.

measurement instrument : TOPCON's luminance meter BM-5 or BM-7 or compatible ,see Figure b.



### FIG.3. The definition of viewing angle



# 7. INTERFACE DESCRIPTION

### Module Interface description

Interface No.	Name	I/O or connect to	Description
1	LEDK	Р	Power for LED backlight(Cathode).
2	LEDA	Р	Power for LED backlight(Anode).
3	GND	Р	Power Ground.
4	NC	/	
5	NC	/	
6	NC	/	
7	SDA	I/O	SPI interface input pin.
8	DOTCLK	I	Dot clock.
9	DE	I	Data enable.
10	VSYNC	I	Vertical sync input
11	HSYNC	I	Horizontal sync input
12	VCC	Р	Power supply
13	RESET	I	Reset signal.
14	GND	Р	Power Ground.
15-32	DB17DB0	I/O	Data bus (DB17DB0).
33	RD	I	RGB Interface.please fix this pin at VDDI or DGND.
34	WR	I	RGB Interface.please fix this pin at VDDI or DGND.
35	RS(SCL)	I	RGB Interface. serial interface clock.
36	CS	I	Chip selection pin. Low enable.
37	XR	I	X-Right
38	YD	I	Y-Down
39	XL	I	X-Left
40	YU	I	Y-Up

### 8. AC CHARACTERISTICS Display Parallel 18/16/9/8-bit Interface Timing Characteristics (8080)

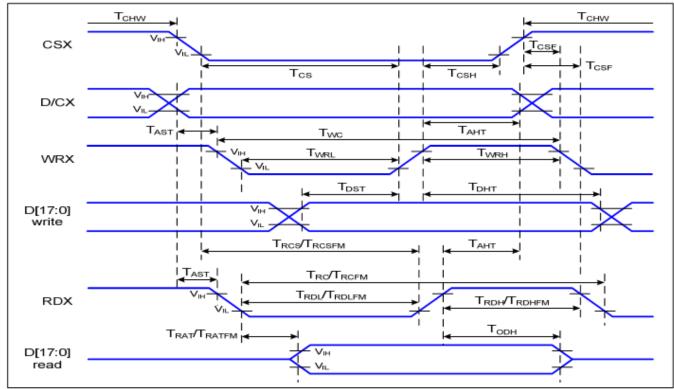


Figure 1 Parallel Interface Timing Characteristics (8080-Series MCU Interface)

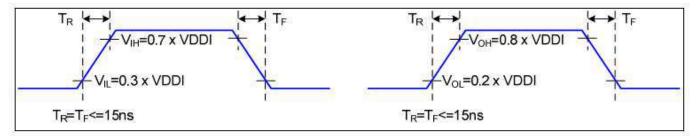


Figure 2 Rising and Falling Timing for I/O Signal

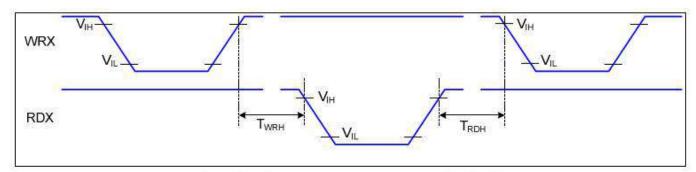
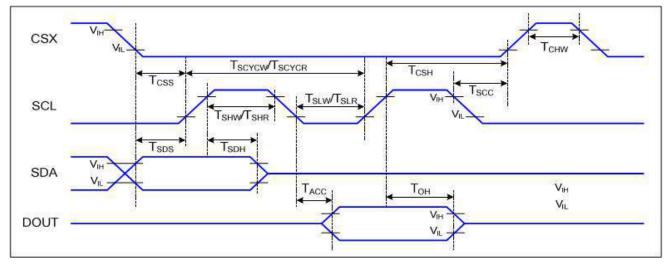


Figure 3 Write-to-Read and Read-to-Write Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta= -30 to 70  $\ensuremath{\mathcal{C}}$ 

Signal	Symbol	Parameter	Min	Max	Unit	Description	
D/CX	T <sub>AST</sub>	Address setup time	0		ns		
DICA	T <sub>AHT</sub>	Address hold time (Write/Read)	10		ns	1750) 1	
	T <sub>CHW</sub>	Chip select "H" pulse width	0		ns		
24 24	T <sub>CS</sub>	Chip select setup time (Write)	15		ns		
CSX	T <sub>RCS</sub>	Chip select setup time (Read ID)	45		ns	5441	
COA	T <sub>RCSFM</sub>	Chip select setup time (Read FM)	355		ns		
	T <sub>CSF</sub>	Chip select wait time (Write/Read)	10		ns		
2	T <sub>CSH</sub>	Chip select hold time	10		ns		
	T <sub>WC</sub>	Write cycle	66		ns		
WRX	T <sub>WRH</sub>	Control pulse "H" duration	15		ns		
	T <sub>WRL</sub>	Control pulse "L" duration	15		ns	2 <del>1</del>	
	T <sub>RC</sub>	Read cycle (ID)	160		ns	16	
RDX (ID)	T <sub>RDH</sub>	Control pulse "H" duration (ID)	90	-1 (	ns	When read ID dat	
		Control pulse "L" duration (ID)	45		ns		
RDX	T <sub>RCFM</sub>	Read cycle (FM)	450		ns	When read from	
(FM)	T <sub>RDHFM</sub>	Control pulse "H" duration (FM)	90		ns	frame memory	
(r m)	T <sub>RDLFM</sub>	Control pulse "L" duration (FM)	355		ns	iname memory	
D[17:0]	T <sub>DST</sub>	Data setup time	10		ns	For CL=30pF	
	T <sub>DHT</sub>	Data hold time	10		ns		
	T <sub>RAT</sub>	Read access time (ID)	5. 5.	40	ns		
3	TRATEM	Read access time (FM)		340	ns		
2	T <sub>ODH</sub>	Output disable time	20	80	ns		

### **Display Serial Interface Timing Characteristics (3-line SPI system)**



### Figure 4 3-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V,	VDD=2.4 to 3.3V,	AGND=DGND=0V,	Ta=-30 to 70	$\mathcal{C}$
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Signal	Symbol	Parameter	Min	Max	Unit	Description
	T <sub>CSS</sub>	Chip select setup time (write)	15		ns	
T <sub>CSH</sub>		Chip select hold time (write)	15		ns	
CSX T <sub>CSS</sub> T <sub>SCC</sub> T <sub>CHW</sub>	T <sub>CSS</sub>	Chip select setup time (read)	60		ns	
	T <sub>SCC</sub>	Chip select hold time (read)	65		ns	
	T <sub>CHW</sub>	Chip select "H" pulse width	40		ns	
	T <sub>SCYCW</sub>	Serial clock cycle (Write)	66		ns	
	T <sub>SHW</sub>	SCL "H" pulse width (Write)	15		ns	
SCL	T <sub>SLW</sub>	SCL "L" pulse width (Write)	15		ns	
SUL	T <sub>SCYCR</sub>	Serial clock cycle (Read)	150		ns	
	T <sub>SHR</sub>	SCL "H" pulse width (Read)	60		ns	
	T <sub>SLR</sub>	SCL "L" pulse width (Read)	60		ns	
SDA	T <sub>SDS</sub>	Data setup time	10		ns	
(DIN)	T <sub>SDH</sub>	Data hold time	10		ns	1
DOUT	T <sub>ACC</sub>	Access time	10	50	ns	For maximum CL=30pF
DOUT	Тон	Output disable time	15	50	ns	For minimum CL=8pF

**Table 5 3-line serial Interface Characteristics** 

### **Display Serial Interface Timing Characteristics (4-line SPI system)**

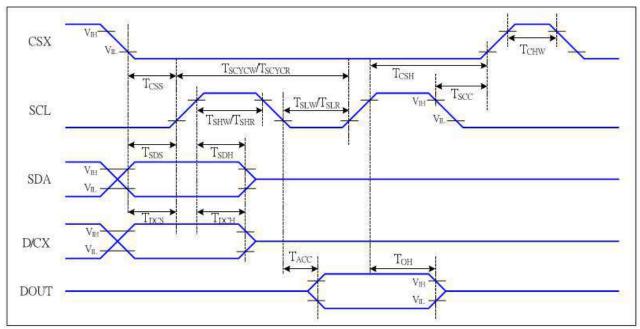


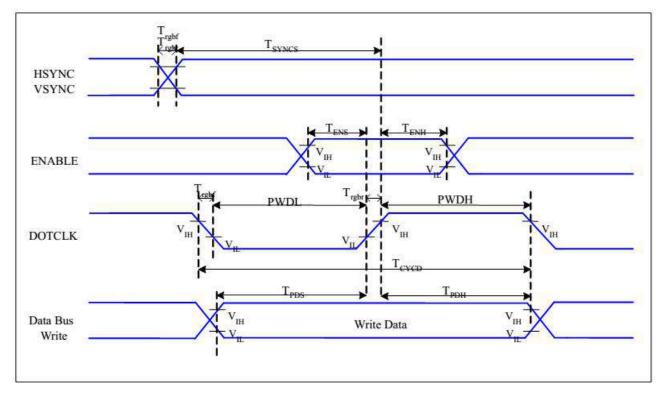
Figure 5 4-line serial Interface Timing Characteristics

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
	T <sub>CSS</sub>	Chip select setup time (write)	15		ns	
T <sub>CSH</sub>		Chip select hold time (write)	15	8	ns	
CSX	T <sub>CSS</sub>	Chip select setup time (read)	60		ns	
	T <sub>SCC</sub>	Chip select hold time (read)	65	2	ns	
	T <sub>CHW</sub>	Chip select "H" pulse width	40		ns	
	T <sub>SCYCW</sub> Serial clock cycle (Write)		66		ns	and a second
0.01	T <sub>SHW</sub>	SCL "H" pulse width (Write)	15		ns	-write command & data
	T <sub>SLW</sub>	SCL "L" pulse width (Write)	15		ns	ram
SCL	T <sub>SCYCR</sub>	Serial clock cycle (Read)	150		ns	and a survey of 0 states
	T <sub>SHR</sub>	SCL "H" pulse width (Read)	60		ns	-read command & data
	T <sub>SLR</sub>	SCL "L" pulse width (Read)	60	53 0	ns	ram
NOV	T <sub>DCS</sub>	D/CX setup time	10	2.	ns	
D/CX	T <sub>DCH</sub>	D/CX hold time	10	0	ns	
SDA	T <sub>SDS</sub>	Data setup time	10	3	ns	
(DIN)	T <sub>SDH</sub>	Data hold time	10		ns	
DOUT	T <sub>ACC</sub>	Access time	10	50	ns	For maximum CL=30pF
DOUT	Тон	Output disable time	15	50	ns	For minimum CL=8pF

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 °C

Table 6 4-line serial Interface Characteristics

### **RGB Interface Characteristics:**



#### Figure 6 RGB Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70  $\,\%$ 

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T <sub>SYNCS</sub>	VSYNC, HSYNC Setup Time	30	-	ns	
	T <sub>ENS</sub>	Enable Setup Time	25	122	ns	
ENABLE	T <sub>ENH</sub>	Enable Hold Time	25		ns	
	PWDH	DOTCLK High-level Pulse Width	60		ns	
DOTCLK	PWDL	DOTCLK Low-level Pulse Width	60		ns	
DUICLK	T <sub>CYCD</sub>	DOTCLK Cycle Time	120		ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T <sub>PDS</sub>	PD Data Setup Time	50		ns	
DB -	T <sub>PDH</sub>	PD Data Hold Time	50	-	ns	

Table 7 18/16 Bits RGB Interface Timing Characteristics

### 9. POWER SEQUENCE

VDDI and VDD can be applied in any order.

VDD and VDDI can be power down in any order.

During power off, if LCD is in the Sleep Out mode, VDD and VDDI must be powered down minimum 120msec after RESX has been released.

During power off, if LCD is in the Sleep In mode, VDDI or VDD can be powered down minimum 0msec after RESX has been released.

CSX can be applied at any timing or can be permanently grounded. RESX has priority over CSX.

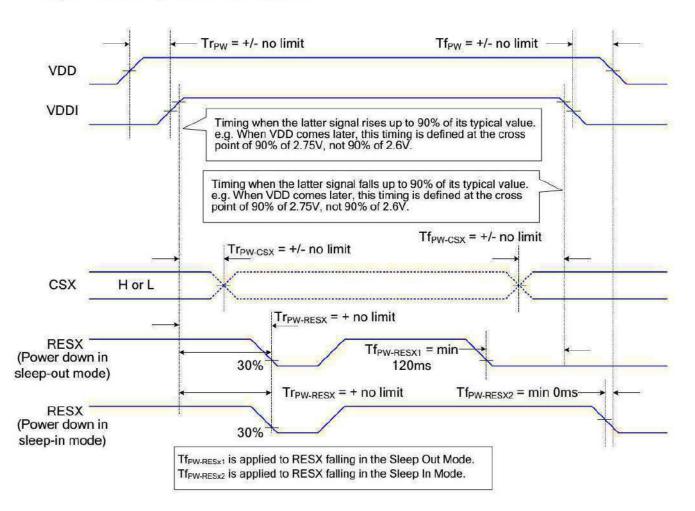
Note 1: There will be no damage to the display module if the power sequences are not met.

Note 2: There will be no abnormal visible effects on the display panel during the Power On/Off Sequences.

Note 3: There will be no abnormal visible effects on the display between end of Power On Sequence and before receiving Sleep Out command. Also between receiving Sleep In command and Power Off Sequence.

Note 4: If RESX line is not held stable by host during Power On Sequence as defined in the sequence below, then it will be necessary to apply a Hardware Reset (RESX) after Host Power On Sequence is complete to ensure correct operation. Otherwise function is not guaranteed.

#### The power on/off sequence is illustrated below



# **10. RELIABILITY TEST CONDITIONS**

No.	Test item	Test con	dition	Inspection after test		
10.1	High temperature storage test	+80°C/240 hours				
10.2	Low temperature storage test	-30°C/240 hours				
10.3	High temperature operating test	+70°C/120 hours				
10.4	Low temperature operating test	-20°C/120 hours	-20°C/120 hours			
10.5	Temperature cycle storage test		-30°C ~ 25°C ~ +80°C/10cycles (30min.) (10min.) (30min.)			
10.6	High temperature high humidity test	+50°C*90% RH/120	+50°C*90% RH/120 hours			
10.7	Vibration test	Frequency : 250 r/mi Amplitude : 1 inch Time: 45min	in	<ol> <li>1.Current changing value before test and after test is 50% larger;</li> <li>2. Function defect :</li> </ol>		
		Drop direction: 1 corner/3 edges/6 s	ides 10 time	Non-display,abnormal-d isplay,missing lines, Short lines,ITO		
		Packing weight(kg)	Drop height(cm)	corrosion;		
10.8	Drop test	<11	80±1.6	3.Visual defect : Air bubble in the LCD,Seal		
1010		11≦G<21	60±1.2	leak,Glass crack.		
		21≦G<31	50±1.0			
		31≦G<40	40±0.8			
10.9	ESD test	Air discharge: ±8KV, Contact discharge: ±				

Remark :

1. The test samples should be applied to only one test item.

2.Sample size for each test item is 3~5pcs.

3.For High temperature high humidity test, Pure water(Resistance>10MΩ) should be used.

4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.

5.B/L evaluation should be excepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence B/L has. 6.Failure judgment criterion: Basic specification, Electrical characteristic, Mechanical characteristic, Optical characteristic.

# **11.INSPECTION CRITERION**

### 11.1. Objective

The TFT test criterion are set to formalize TFT quality standards for ODNA with reference to those of the customer for inspection, release and acceptance of finished TFT products in order to guarantee the quality of TFT products required by the customer.

#### 11.2. Scope

The criterion is applicable to all the TFT products manufactured by ODNA.

#### 11.3. Equipment for Inspection

Electrical tester, electrical testing machines, vernier calipers, microscopes, magnifiers, anti-static wrist straps, finger cots, labels, tri-phase cold and hot shock machine, constant temperature and humidity chamber, backlight table, ovens for high-low temperature experiments, refrigerators, constant voltage power supply (DC)), desk Lamps, etc.

#### 11.4. Sampling Plan and Reference Standards

11.4.1.1 Sampling plan:

Refer to National Standard GB/T 2828.1---2012/ISO2859-1:1999, level II of normal levels:

Product Category	Consumer Electronics	Non-consumer Electronics	Industrial	Automobile
AQL	MA=0.4 MI=1.5	MA=0.4 MI=1.0	MA=0.25 MI=0.65	MA=0.15 MI=0.40

11.4.1.2 GB/T 2828.1---2012/ISO2859-1:1999 Sampling check procedure in count

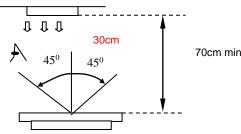
11.4.1.3 GB/T 18910. Standard for LCM parts

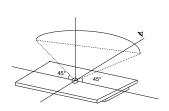
11.4.1.4 GB/T24213-2008 Basic Environmental Test Procedures for Electrical and Electronic Products 11.4.1.5 IPC-A-610E Acceptability of Electronic Assemblies

#### **11.5.** Inspection Conditions and Inspection Reference

11.5.1Cosmetic inspection: shall be done normally at  $23\pm5^{\circ}$ C of the ambient temperature and 45~75%RH of relative humidity, under the ambient luminance between 500lux~1000lux and at the distance of 30cm apart between the inspector's eyes and the LCD panel and normally in reflected light. For backlight LCM, cosmetic inspection shall be done under the ambient luminance less than 100lux with the backlight on.

11.5.2 The TFT shall be tested at the angle of 45°left and right and 0-45° top and bottom as the following picture showing:





11.5.3 Definition of viewing area (VA)

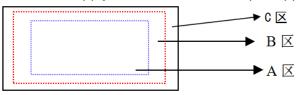
A area: Active area (AA area)

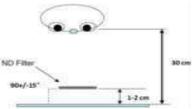
B area: Viewing area (VA area)

C area: Non-viewing area (not viewing after customer assembly)

If there is any appearance viewing defect which do not affect product quality and customer assembly in C area, it's accepted in generally.

The criteria apply to A and B area except chipping and crack.





11.5.4 Inspection with naked eyes(exclusive of the inspection of the physical dimensions of defects carried out with magnifiers)

11.5.5 ND card use method(refer to right conner image ) and scope: Multi-bright dot; Mura(Black/Gray pattern uneven); dark line and so on.

11.5.6 Undefined items or other special items, refer to mutual agreement and limited sample. If criterion does not match product specifications/ technical requirement, both should be subject to special inspection criterion agreed by customer.

### **11.6 Defects and Acceptance Standards**

11.6.1 Electrical properties test

11.6.1.1 Test voltage(V): Refer to the instruction of testers and the product specification or drawing and the display content and parameters and display effects shall conform to the product specification and drawing.

11.6.1.2 Current Consumption(I): Refer to approved product specifications or drawings.

11.6.1.3 Fu	nction items(	Defect category MA)		-	
No.	Defects	Descriptions	Pictures	Inspection method/tools	Defect category
11.6.1.3.1	No display /reaction	shows no picture/display in normal connected situation.		Naked eyes/ testers	МА
11.6.1.3.2	Missing segment	Shows missing lines in normal display		Naked eyes/ testers	МА
11.6.1.3.3	Dark line	Only visible on gray pattern, 1 or more vertical/horizontal lines: 5%ND, not visible, OK	/	Naked eyes/ testers	МА
11.6.1.3.4	POL angle defect	Not accepted		Naked eyes/ testers	МА
11.6.1.3.5	Image retention (sticking)	Chess pattern stays for 30mins and change to 50% gray pattern, disappear in 10s, OK; if time>10s, NG		Naked eyes/ testers	МА
11.6.1.3.6	Flicker	Refer to Limit sample if essential or flicker value <-30dB (measured by CA310A); OK		Naked eyes/ CA310A	MA
11.6.1.3.7	Display abnormal	Not accepted		Naked eyes/ testers	МА
11.6.1.3.8	Cross-talk	Refer to limited sample	+	Naked eyes/ limited sample	МА
11.6.1.3.9	Display dim/bright	Refer to limited sample	/	Naked eyes/ limited sample	MA
11.6.1.3.10		Refer to limited sample	/	Naked eyes/ limited sample	MA
11.6.1.3.11	Huge current	Out of spec, not accepted	/	Ammeter	MA
11.6.1.3.12	TP function defect	Not accepted	/	Naked eyes/ Touch/ test program	MA

11.6.1.3 Function items (Defect category MA)

test program

### 11.6.2 LCD dot/line defect

|--|

Item	Inspection criterion							
Size	S <5"	5≤S<10"	10≤S<15"	S≥15"				
Color pixel dot defect(RGB dot)	1	2	2	3				
2 connected bright dot	0	1	1	1				
3 connected bright dot or more	0	0	1	0				
Bright dot quantity	1	2	3	4				
Random dark dot quantity	2	3	4	5				
2 connected dark dot	1	1	2	2				
3 connected dark dot or more	0	0	0	0				
Dark dot quantity	3	4	5	<u>6</u>				
Multi-bright dot	ND 5% hidde	en, OK						

2) Dark dot: Power on TFT and gray or black dot in RGB display

3) Multi-bright dot: Power on TFT and fluorescent tiny dot in black display(only visible in black display)

11.6.2.2 LCD appearance dot defect (defect category: MI)

								Pic	ture	Inspection		
No.	ltem	Size	S <5"	5≤S<`	10"	10≤S 15"	<	<u>S≥</u> ′	<u>15"</u>			method/tool s
		D≤0.15	ignore	ignore	е	D≤0.2;		D<	<n 2·<="" td=""><td colspan="2"></td><td></td></n>			
		0.15< D≤0.25	3	3		Not count	t	'' <u>D≤0.2;</u> ignore			<b>•</b>	Naked eyes
	Dot defect	0.25< D≤0.30	1	2			0.2~0.35		~0.35	+	a	/film card /magnifier
11.6.2.2.1	(black dot, white dot)	0.30< D≤0.35	0	1		Q'ty ≤	≦4	<u>Q'ty</u>	<u>Q'ty ≤ 5</u>			
	white doty	0.35< D≤0.50	0	0		1		<u>2</u>				
		D>0.5	0	0		0		0				
			emark: D≤0.15mm, not count. Multi-dot as bulk is not accepted. ount dot quantity≤ 5; 2 round dots or linear dots in 1 cm is judged as multi-dot.									
		Length (mm)	Width (mm)	<u>S &lt;5"</u>	<u>5≤8</u> 10"		<u>10≤S</u> 15"	<u>}&lt;</u>	<u>S≥15"</u>			
		Not count	W≤0.03	Ignored	lgn	ored	Igno	red	Ignore	<u>ed</u>		
		L≤5	<u>0.03≤W</u> <u>&lt;0.05</u>	3	3		Igno	red	Ignore	<u>ed</u>	1	Naked eyes
11.6.2.2.2	Line defect (visible when	L≤5	<u>0.05≤W</u> <u>&lt;0.08</u>	0	1		3		<u>3</u>			<pre>/film card /magnifier</pre>
	power on)	L≤8	<u>0.05≤W</u> <u>&lt;0.08</u>	0	0		1		<u>2</u>			
		L>8	<u>W&gt;</u> 0.08	0	0		0		<u>0</u>			
			nark/foldir	-			-		-		ngle again control or re	st light, show efer to

		Size(mm )	<u>S &lt;5"</u>	<u>5≤S&lt;10"</u>	<u>10≤S&lt;</u> 15"	<u>S≥15"</u>	
	Delerizer	<u>D≤0.20</u>	Ignored	Ignored	Ignored	Ignored	
11.0.2.2.3	Polarizer convex- concave	<u>0.20&lt;</u> D≤0.5	2	2	3	<u>5</u>	Naked eyes
	dot defect, polarizer	<u>0.50&lt;</u> D≤0.8	0	1	2	<u>3</u>	/film card /magnifier
	bubble defect	<u>0.8&lt;</u> D≤1.5	0	0	1	2	
		<u>D&gt;</u> 1.5mm	0	0	0	<u>o</u>	

### 11.6.3 Chipping defect

No.	Item	Accepted	d crit	terion(mm)			MAJ	MIN
	ITO conductive side	х	/		≤1/8L	/		
11.6.3.1	2 A A A A A A A A A A A A A A A A A A A	Y	Y Y≤1/6		1/6W <y≤1 4w<="" td=""><td>1/4W <y< td=""><td></td><td><math>\checkmark</math></td></y<></td></y≤1>	1/4W <y< td=""><td></td><td><math>\checkmark</math></td></y<>		$\checkmark$
		Accept	2		2	$(1/8L)$ / $7/6W$ $1/4W < Y$ $2 0$ $0$ $(Y \le 1/4W)$ $0$ $(1/6L)$ / $(1/2W) < Y \le W$ $W < Y$ $(1/2W) < W \le W$ $W < Y$		
44.0.0.0		х	/		≤1/6L	/6L /		
11.6.3.2	Corner chipping (ITOpins position)	Accept2Accept2X/Position)YYY $\leq 1/2$ Accept2Accept2Accept2Corner chipping as per 6.3.3; at into black borde chipping effect to perform as per form as per form as per form into the second chipping)YYY <tr< td=""><td>1/2W</td><td>1/2W <y≤w< td=""><td>W <y< td=""><td></td><td><math>\checkmark</math></td></y<></td></y≤w<></td></tr<>	1/2W	1/2W <y≤w< td=""><td>W <y< td=""><td></td><td><math>\checkmark</math></td></y<></td></y≤w<>	W <y< td=""><td></td><td><math>\checkmark</math></td></y<>		$\checkmark$	
	Corner chipping	Accept	2		1	0		
		as per 6. into blacl chipping	Corner chipping occurred in sealed edge position as per 6.3.3; at the same time it should not enter into black border of the frame and the corner chipping effect the electric connection position perform as per 6.3.1.					
		х		/	≤1/8L	/		
		(outside chipping) Y (inside		Not enter into		H <y< td=""><td></td><td></td></y<>		
11.6.3.3				sealant		1/2H <y< td=""><td></td></y<>		
	1 4	Z		≤T	≤1/2T	/		1
11.6.3.3		Accept	Accept 2 1 0		_	V		
		sealing a occurred	area I in tl	are same. he opposite	When the chip e of stage, Y a	ping s per the		
11.6.3.4	conductive side	Х		/	≤1/6L	/		$\checkmark$

	(back side chipping	Υ	Y≤1/3W	1/3W <y≤2 3w<="" th=""><th>2/3W <y< th=""><th></th><th></th></y<></th></y≤2>	2/3W <y< th=""><th></th><th></th></y<>				
		Accept	2	2	0				
		Chipping int	to ITO side ,re	efer to 6.3.1					
	Protruding LCD	Х	1	≤1/8L	/				
	poor cutting and LCD burrs	Y	≤1/6W	1/6W <y≤1 5w<="" td=""><td>1/5W <y< td=""><td></td><td></td></y<></td></y≤1>	1/5W <y< td=""><td></td><td></td></y<>				
11.6.3.5		Z	/	/	/				
		Accept	1	1	1				
		the outside of drawing.	protruding co	ntrol as per th	ne tolerance				
11.6.3.6	Crack	Not allow to occur cracks without direction; the crack expand to inside is NG, but to outside is OK (confirmed as per the damaged standard) $$							
	Remark:1)X means the length of chipping; Y means the width; Z means the thickness; W means the step width of the two glasses; H means the distance from the glass edge to the seal inner edge;								
t means gl	ass thickness.								

#### 11.6.4 Backlight components

No.	Item	Description	Accepted criterion	MAJ	MIN
11.6.4.1	No backlight wrong Color	1	Rejected		
11.6.4.2	Color deviation	When powered on, the LCD color differs from its sample and found that the color not conforming to the drawing after testing.	Refer to sample and drawing.		
11.6.4.3	Brightness deviation	When powered on, the LCD brightness differs from its sample and is found after testing not conforming to the drawing; or if it conforms to the drawing but the brightness over $\pm 40\%$ than its typical value.	Refer to sample and drawing.		$\checkmark$
11.6.4.4	Uneven brightness	Uneven on the same LCD and out of the specification of the drawing. The no specification evenness= (the max value-the min value)/ mean value< 70%.	Refer to sample and drawing.		$\checkmark$
11.6.4.5	Spot/line /scratch	When power on, it has dirty spot, scratches and so on spot and line defects.	Refer to 6.2.2		$\checkmark$

11.6.5 Metal frame (Metal Bezel)

No.	Item	Description		Accepted criterion	MAJ	MIN
11.6.5.1	Material & surface treatment	Metal frame/surface treatment do not conform to Re the specifications.		Rejected	$\checkmark$	
11.6.5.2	Tab twist Unconformity/ Tab not twisted	Wrong twist method or direction and twist tabs are not twisted as required.		Rejected	$\checkmark$	
11.6.5.3	Bezel paint loss	1.Front surface: Paint peel off and scratch to t	he			$\checkmark$
11.6.5.4	Bezel scratch	bottom Dot:D≤0.5mm, exceeds 3; Line:L≤3.0mm,W≤0.05mm				
11.6.5.5	Painting peel off, discoloration, dent, and scratch	exceeds 2; 2.Front dent, air bubble and side with paint peeling off scratch to the bottom Dot: D≤1.0mm, exceeds 3; Line:L≤10.0mm,W≤0.05mm, exceeds 2;		Rejected		$\checkmark$
11.6.5.6	Burr	Burr(s) on metal bezel is so long as to get into viewing are	ea.	Rejected		$\checkmark$
11.6.6 F	PC		1		I	1
No.	Item	Description	Accep	oted criterion	MAJ	MIN
11.6.6.1	Model & P/N	Material model & P/N	Keep the same with drawing and technical requirement		$\checkmark$	
11.6.6.2	Dimension/ position	Dimension in drawing spec	f≤1/3w, h ≤1/3H, dimension in drawing spec-> OK Conducive material and ITO/PDA connective area must over than 1/2. Entire dimension must be in spec tolerance.			V
11.6.6.3	FPC appearance	Hot pressing material get broken, folding line open; FPC golden finger oxidate, broken ,scratch ,foreign material which cause line short	Broken length<2mm; FPC line is OK- > Accepted Crack and line broken-> Rejected			$\checkmark$
11.6.6.4	FPC burr	Burr near FPC edge area		cover line and burr 1 ≤1.0mm->Accepted		$\checkmark$
11.6.6.5	FPC falling off	FPC bonding area falling off ; silica gel breaking	Rejec	ted		$\checkmark$
11.6.6.6	Sealant missing ITO line	Sealant is not covered all ITO line	Rejec	ted	$\checkmark$	
11.6.6.7	Missing sealant	No sealant	Rejec	ted	$\checkmark$	
11.6.6.8	Sealant	Sealant height > product total height	Rejec	ted	$\checkmark$	

No.	Item	Description	Accepted criterion	MAJ	MIN
11.6.7.1	Soldering bridge	Solder between adjacent pads and components	Rejected		~
11.6.7.2	Solder ball/splash	Solder ball/tin dross causing short circuit at the solder point. There are active solder ball and splash.	Rejected		
11.6.7.3	Soldering excursion	Soldering slant > 1/3 soldering pad	Rejected		$\checkmark$
11.6.7.4	Component wrong attaching	Component on PCB differs with drawing: wrong one, extra one, lack one, opposite polarity	Rejected	$\checkmark$	
		JUMP short circuit on PCB: extra soldering ,lack soldering.	Rejected	$\checkmark$	
11.6.7.5	Component falling off	Soldering but component is missing	Rejected	$\checkmark$	
11.6.7.6	Wrong component	Component model/spec differs from product specification	Rejected	$\checkmark$	

### 11.6.8 General Appearance

No.	Item	Description	Accepted criterion	MAJ	MIN
11.6.8.1	Dimension	According to drawing	Accepted	$\checkmark$	
11.6.8.2	Surface stain	Defect mark or label are not removed residual glue, and finger print,etc;	Rejected		$\checkmark$
11.6.8.3	Assembly foreign material	Dot/linear stain after assembly backlight and diffuse film TP assembly fogy stain	Invisible when power on->OK Refer to 6.2.2 dot/line spec		$\checkmark$
11.6.8.4	Mixture	Different model product in the same shipment	Rejected	$\checkmark$	
11.6.8.5	Product mark	Missing, unclear, incorrect, or misplaced part	Rejected		$\checkmark$
11.6.8.6	Component mark	Silk screen mark clear, resistance measured value in spec	Accepted (Refer to customer special requirement		$\checkmark$
11.6.8.7	Newton's rings	Area<1/6 screen area quantity≤1	Accepted		$\checkmark$

11.6.8.8	Mura	1.In black display ND 5% invisible ->OK; visible->NG 2.Naked eyes inspection RGB display invisible Black display, area<1/4 screen area	Refer to limited sample	$\checkmark$
11.6.8.9	Light leak	1.LCD edge(near backlight) shadow by LCD lamps irregular illuminate 2.Judge in black/white/gray display (slight leaky is yellowish, greenish, bluefish ->NG);	Refer to limited sample Tepo 浮起源走 Panel 倒達渦走	
11.6.8.10	Polarizer	<ol> <li>Polarizer slant.Cover VA and not over LCD edge</li> <li>No unmovable stain or finger print in polarizer VA</li> <li>Bubble/warped but not enter VA</li> </ol>	Accepted	$\checkmark$
11.6.8.11	TP defect	1.TP crack 2.TP stain(fogy&unremovable) 3.TP glue overflow to VA	Rejected	$\checkmark$

Remark: Anything which is not clearly defined in 6.5~6.8 should refer to IPC-A-610E.Consumer Electronics, Non-consumer Electronics refer to class 1 and Industrial, Automobile refer to Class 2.

### 11.7. Others

Items not specified in this document or released on compromise should be inspected with reference to mutual agreement and limit samples.

# **12. HANDLING PRECAUTIONS**

### **12.1 Mounting method**

The LCD module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board. Extreme care should be needed when handling the LCD modules.

### 12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[recommended below] and wipe lightly :

- •.lsopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent :

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns

Do not use the following solvent on the pad or prevent it from being contaminated :

Soldering flux

•.Chlorine (CI) , Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

### 12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you :

Connect any unused input terminal to Vdd or Vss, do not input any signals before power is turned on, and ground your body, work/assembly areas, assembly equipment to protect against static electricity.

### 12.4 Packing

Module employ LCD elements and must be treated as such.

• Avoid intense shock and falls from a height.

•. To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity.

#### 12.5 Caution for operation

•. It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.

•. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.

•.Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.

•. If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.

•.A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

•.Usage under the maximum operating temperature, 50%Rh or less is required.

•.When fixed patterns are displayed for a long time, remnant image is likely to occur.

#### 12.6 Storage

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

•.Storing in an ambient temperature 10°C to 30°C, and in a relative humidity of 45% to 75%. Don't expose to sunlight or fluorescent light.

•.Storing in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it . And with no desiccant.

•.Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.

•.Storing with no touch on polarizer surface by the anything else.

It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

### 12.7 Safety

•. It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.

•. When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

### **13. PRECAUTION FOR USE**

**13.1** A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

**13.2** On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

•.When a question is arisen in this specification.

•.When a new problem is arisen which is not specified in this specifications.

•.When an inspection specifications change or operating condition change in customer is reported to ODNA, and some problem is arisen in this specification due to the change.

•.When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

### **14. PACKING SPECIFICATION**

Please consult our technical department for detail information.

# **15. INITIALIZATION CODE**

WriteComm(0x11); Delay(120); //Delay 120ms //Display Setting//
WriteComm(0x36); WriteData(0x00); WriteComm(0x3a); WriteData(0x66); WriteComm(0x21); //ST7789V Frame rate setting//
WriteComm(0xb2);         WriteData(0x0c);         WriteData(0x00);         WriteData(0x33);         WriteData(0x33);         WriteComm(0xb7);         WriteData(0x75);
//ST7789V Power setting// WriteComm(0xb0); WriteData(0x11); WriteComm(0xbb); WriteComm(0xc0); WriteOata(0x2c); WriteComm(0xc2); WriteComm(0xc2); WriteComm(0xc3); WriteData(0x13); WriteComm(0xc4); WriteData(0x20); WriteData(0x20); WriteData(0xc6); WriteData(0xo1); WriteData(0xa4); WriteData(0xa4); WriteData(0xa1); //ST7789V gamma setting//
WriteComm(0xE0);         WriteData(0x70);         WriteData(0x08);         WriteData(0x0D);         WriteData(0x0C);         WriteData(0x07);         WriteData(0x37);         WriteData(0x4C);         WriteData(0x39);         WriteData(0x15);         WriteData(0x2A);         WriteData(0x2D);
WriteComm(0xE1); WriteData(0x70); WriteData(0x0D); WriteData(0x12); WriteData(0x08); WriteData(0x08); WriteData(0x15);

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WriteData(0x34); WriteData(0x34); WriteData(0x4A); WriteData(0x36); WriteData(0x12); WriteData(0x13); WriteData(0x2B); WriteData(0x2F); Delay(120); WriteComm(0x29); Delay(120);

## **15. HSF COMPLIANCE**

•.This products complies with ROHS 2011/65/EU and 2015/863/EU、REACH 1907/2006/EC requirements, and the packaging complies with 94-62-EC.